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SOD-523

MARKING:S1



## **BAS716** FAST SWITCHING DIODE

#### **FEATURES**

- Small Package
- Low Reverse Current
- Fast Switching Speed
- Surfce Mount Package Ideally Suited for Automatic Insetion

#### MAXIMUM RATINGS ( $T_a$ =25 $^{\circ}$ C unless otherwise noted )

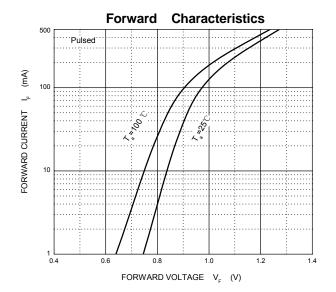
Symbol	Paramete	Value	Unit
$V_{RM}$	Non-Repetitive Peak Reverse Voltage	n-Repetitive Peak Reverse Voltage 100 V	
$V_{RRM}$	Peak Repetitive Reverse Voltage	75 V	
V <sub>RWM</sub>	Working Peak Reverse Voltage		
$V_{R(RMS)}$	RMS Reverse Voltage	53	V
lo	Average Rectified Output Current	200	mA
I <sub>FSM</sub>	Non-Rpetitive Peak Forward Surge Current @t=8.3ms	1	А
P <sub>D</sub>	Power Dissipation	225	mW
R <sub>OJA</sub>	Thermal Resistance from Junction to Ambient	556	°C/W
T <sub>j</sub>	Junction Temperature	150	℃
T <sub>stg</sub>	Storage Temperature	-55~+150	°C

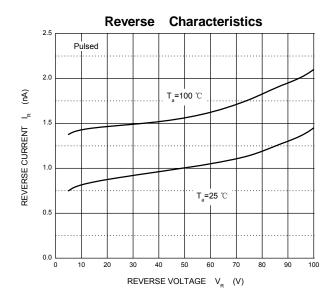
#### **ELECTRICAL CHARACTERISTICS(Ta=25℃ unless otherwise specified)**

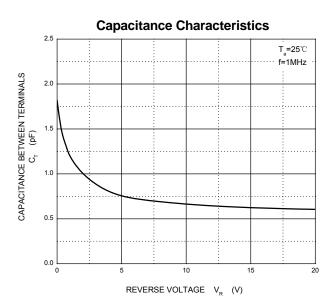
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	$V_{(BR)}$	I <sub>R</sub> =100μA	75			V
Reverse current	I <sub>R</sub>	V <sub>R</sub> =75V			5	nA
		V <sub>R</sub> =100V			80	nA
E-manda de	V <sub>F</sub>	I <sub>F</sub> =1mA			0.9	V
		I <sub>F</sub> =10mA			1	V
Forward voltage		I <sub>F</sub> =50mA			1.1	V
		I <sub>F</sub> =150mA			1.25	V
Total capacitance	C <sub>tot</sub>	V <sub>R</sub> =0V,f=1MHz		2		pF
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = I <sub>R</sub> =10mA, I <sub>rr</sub> =0.1*I <sub>R</sub>			3	μs

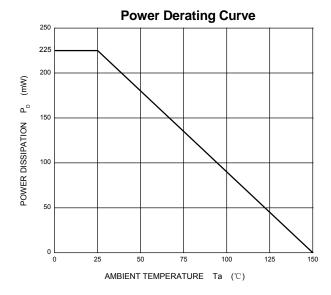


#### **Typical Characteristics**

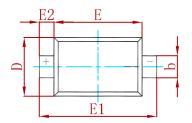


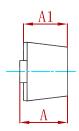


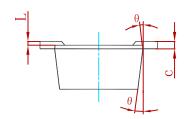




### **PACKAGE MECHANICAL DATA**

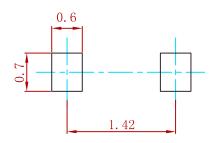






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		0.008	REF	
L	0.010	0.070	0.001	0.003	
θ	7° F	RFF	7° F	RFF	

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
BAS716	SOD-523	3000



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